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ODAKA et al.(10) **Pub. No.: US 2015/0076476 A1**(43) **Pub. Date: Mar. 19, 2015**(54) **ORGANIC ELECTROLUMINESCENCE
DISPLAY DEVICE AND METHOD OF
MANUFACTURING ORGANIC
ELECTROLUMINESCENCE DISPLAY
DEVICE****Publication Classification**

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TOKUDA**, Tokyo (JP)(21) Appl. No.: **14/489,550**(22) Filed: **Sep. 18, 2014**(30) **Foreign Application Priority Data**

Sep. 19, 2013 (JP) 2013-194351

(57) **ABSTRACT**

A method of manufacturing an organic electroluminescent display device includes the steps of: forming a first insulating layer on a substrate; forming a first patterning layer; forming a second patterning layer; forming a trench portion; and forming an electrode layer on the second patterning layer and in the trench portion, wherein in the step of forming the trench portion, an end of the first patterning layer exposed within the trench portion is etched to an outside more than an end of the second patterning layer exposed within the trench portion in a plan view, and in the step of forming the electrode layer, the electrode layer formed within the trench portion is isolated from the electrode layer formed outside of the trench portion.

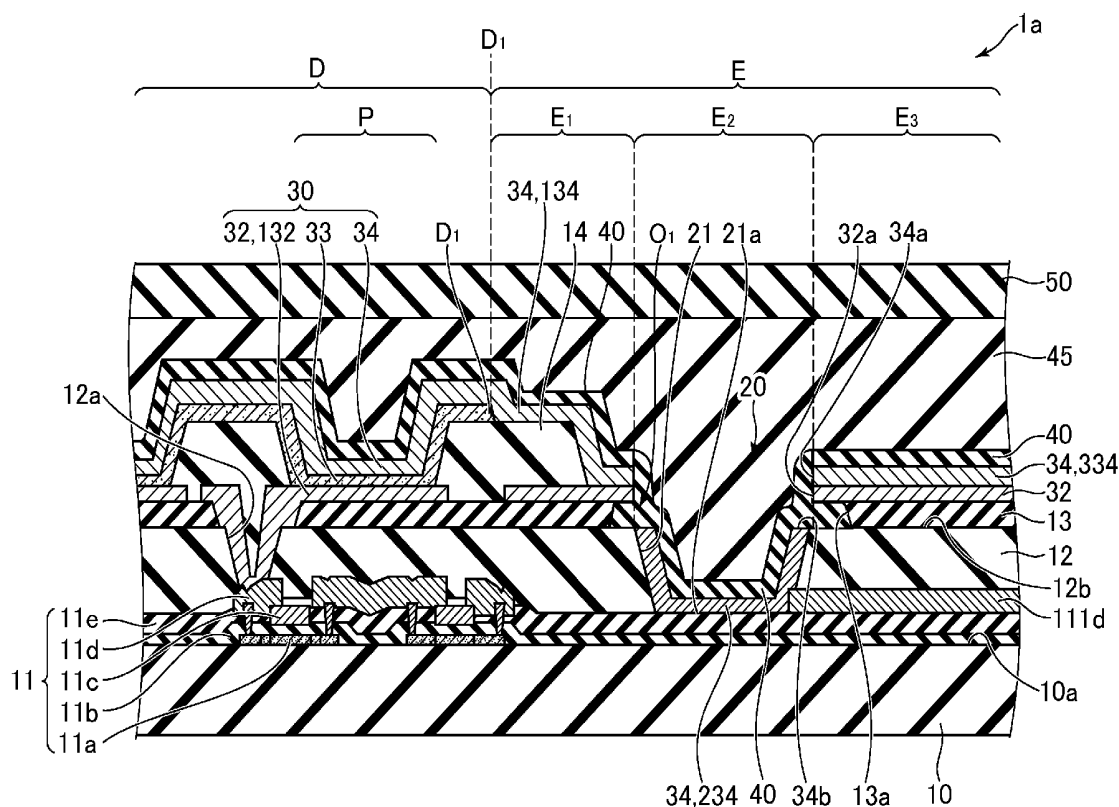


FIG.1

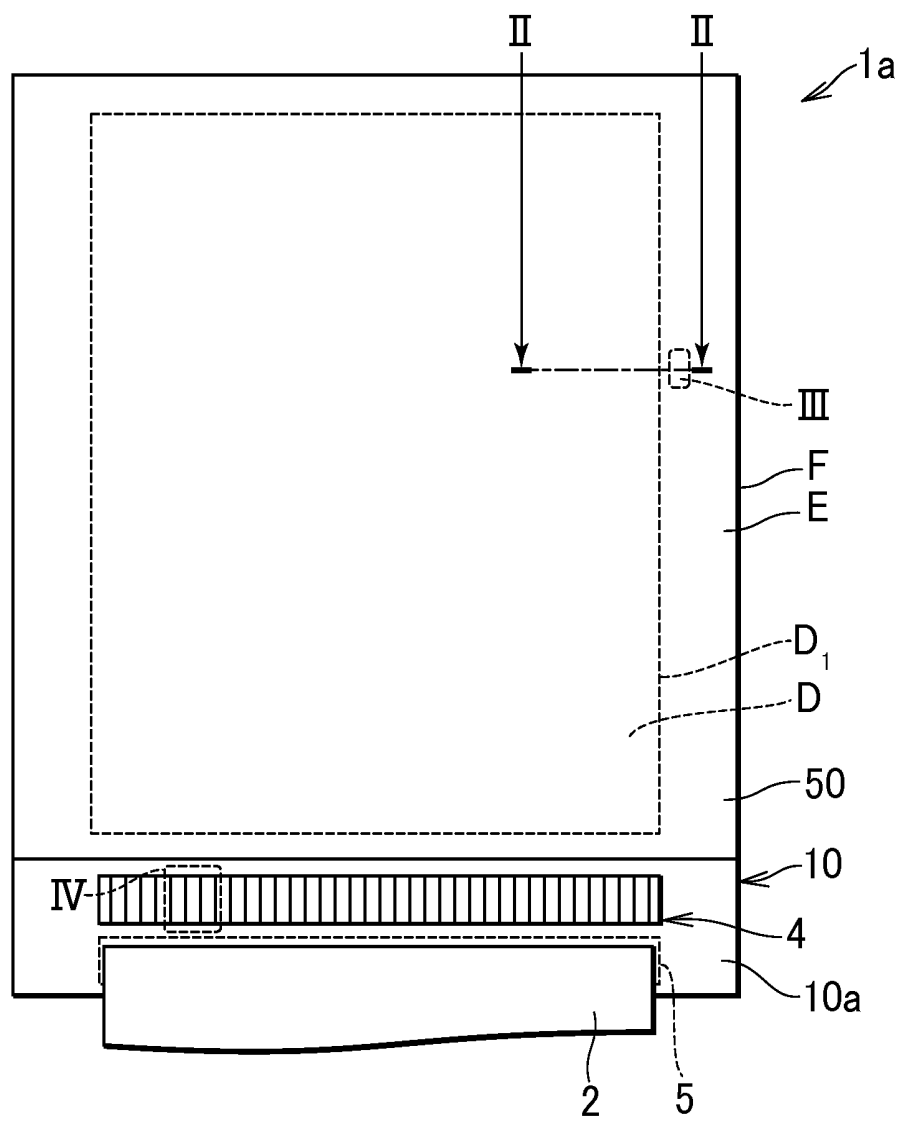


FIG.2

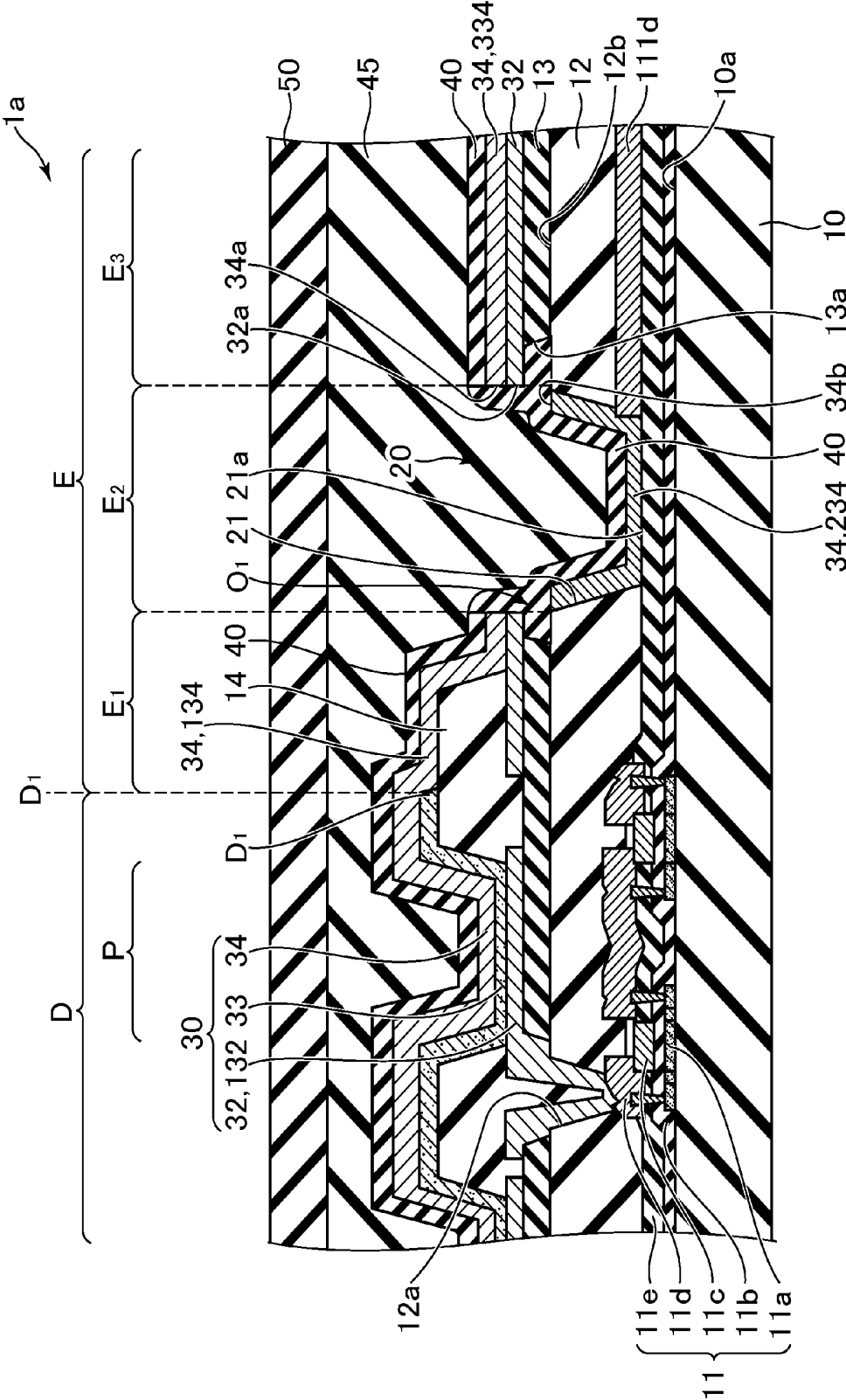


FIG.3

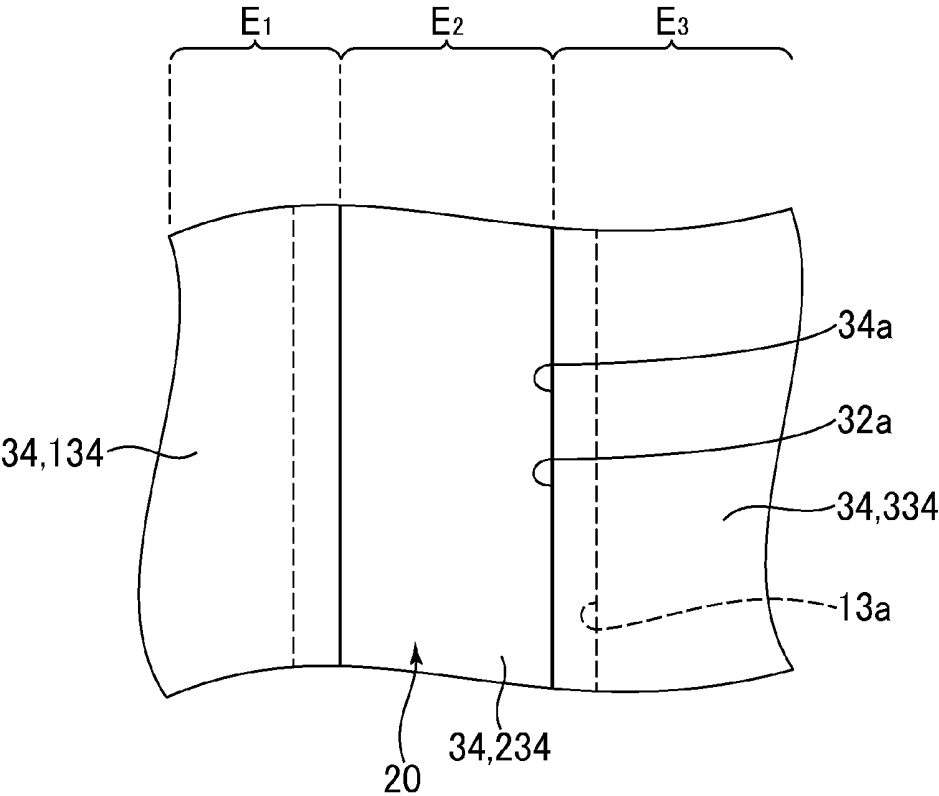


FIG.4

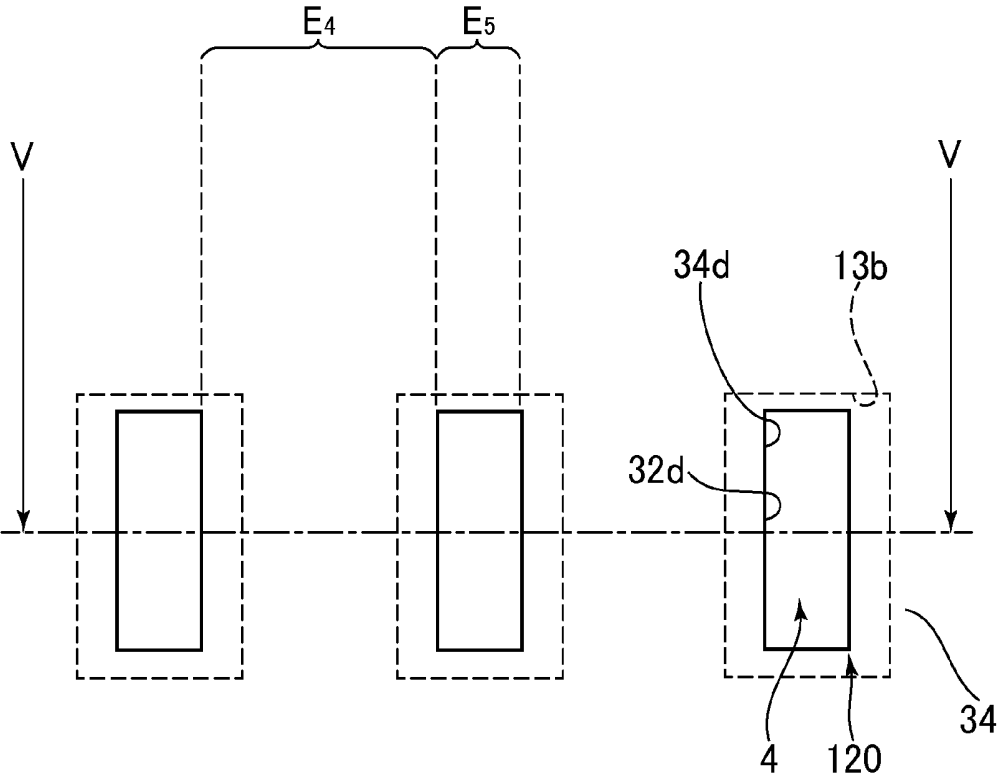


FIG.5

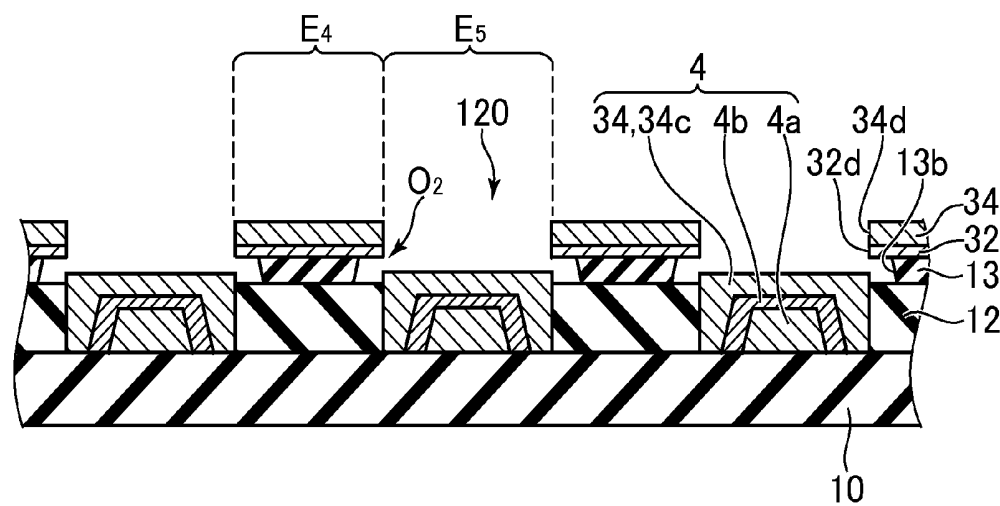


FIG.6

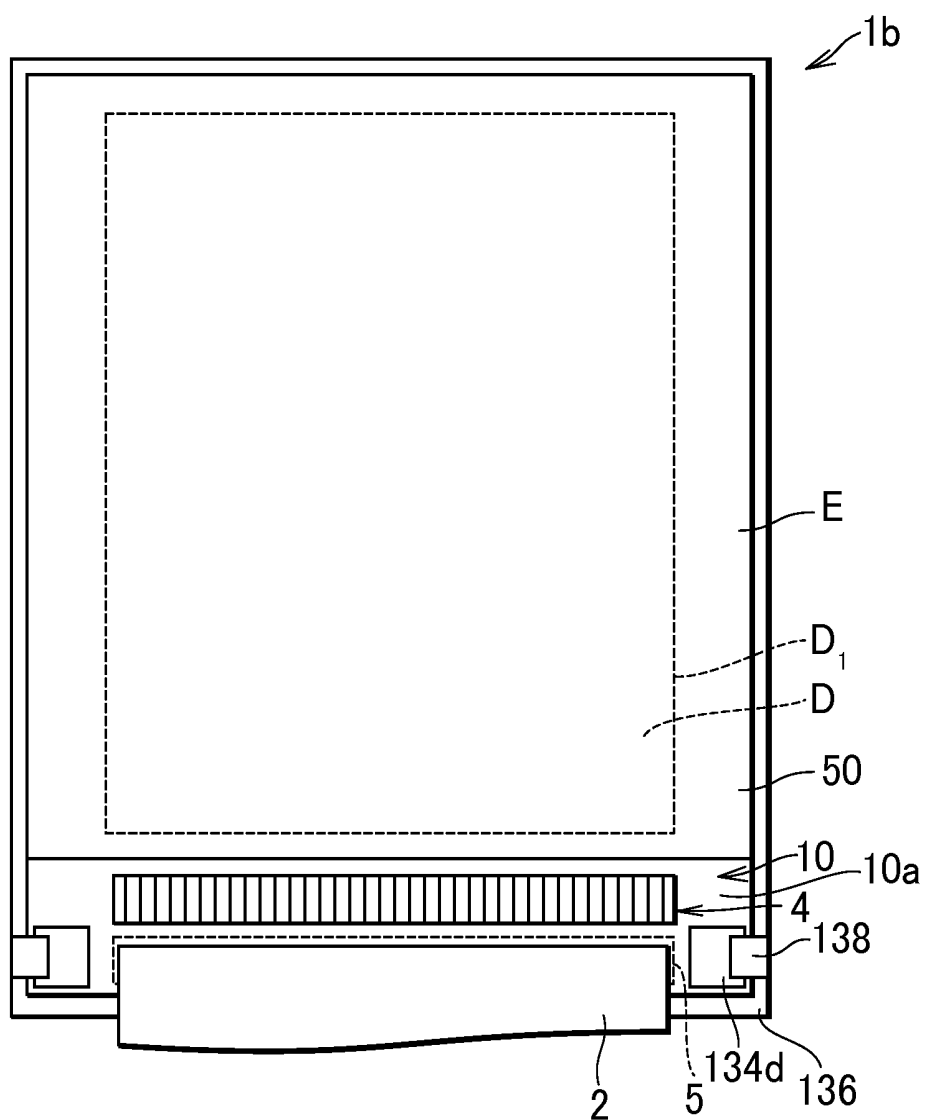


FIG. 7

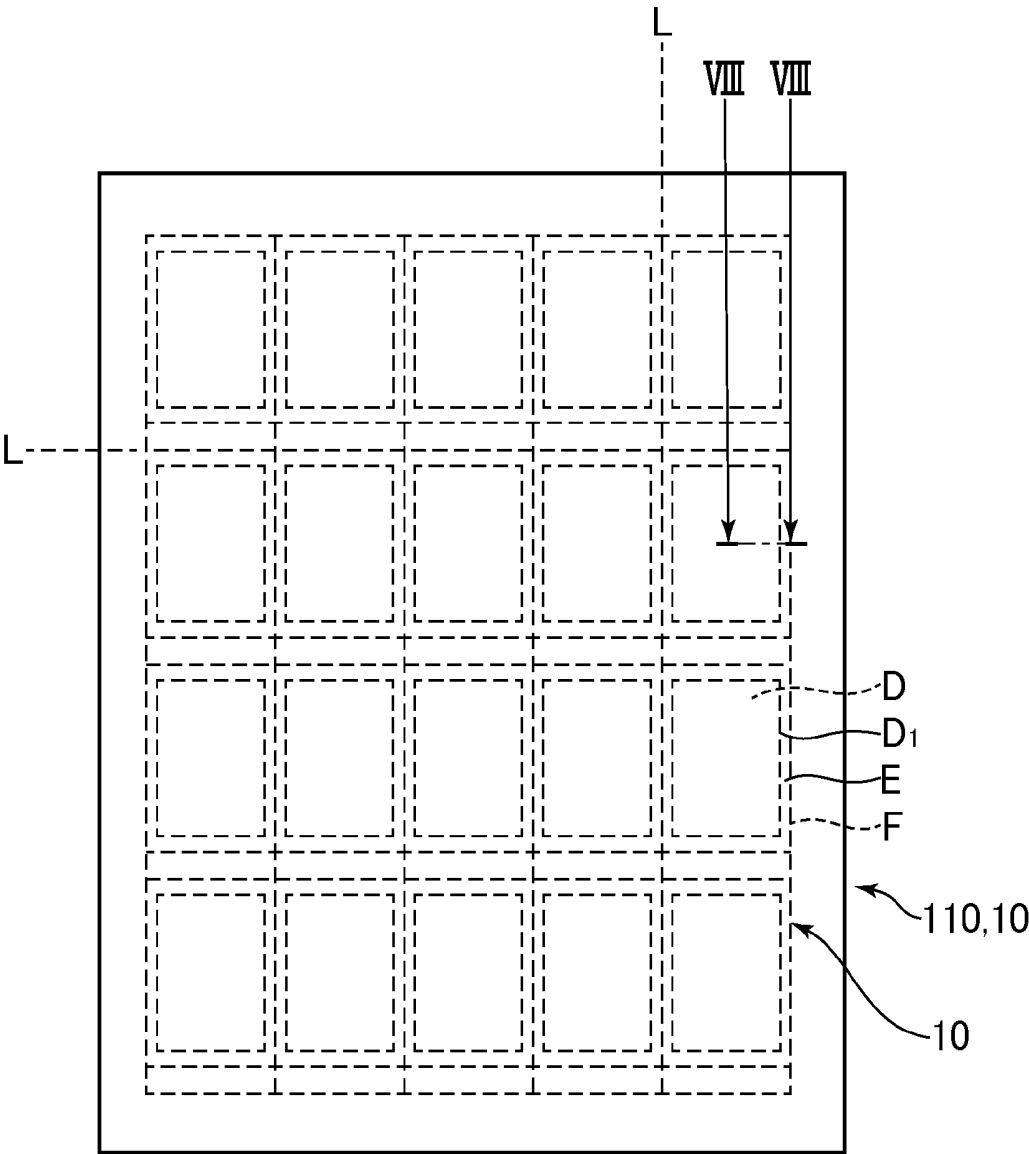


FIG.8

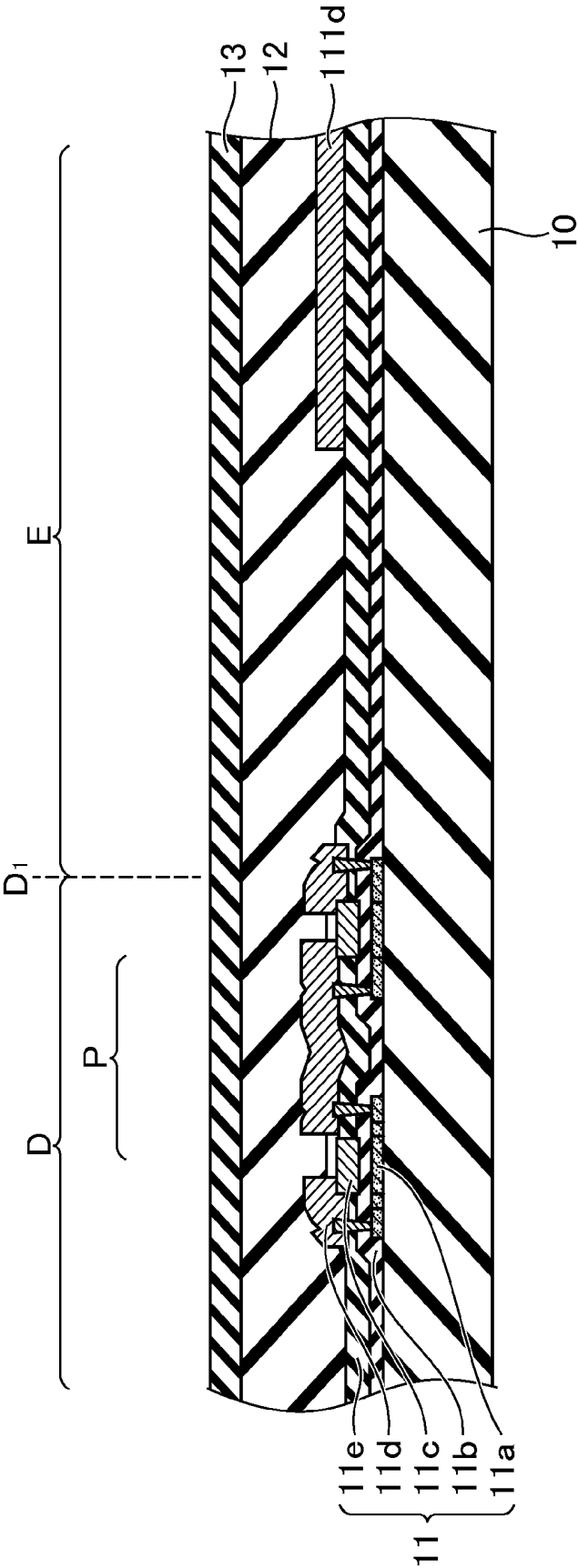


FIG. 9

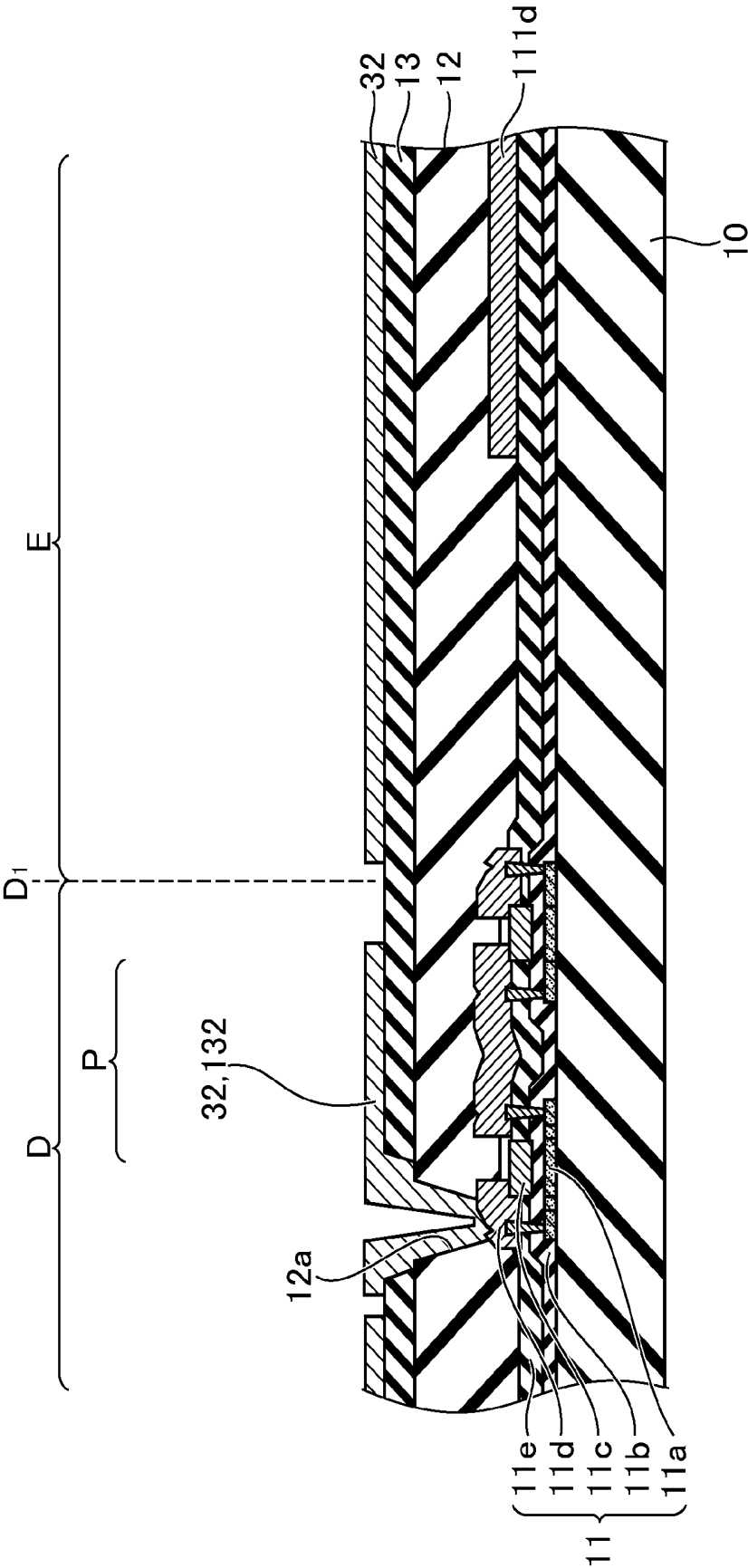


FIG. 11

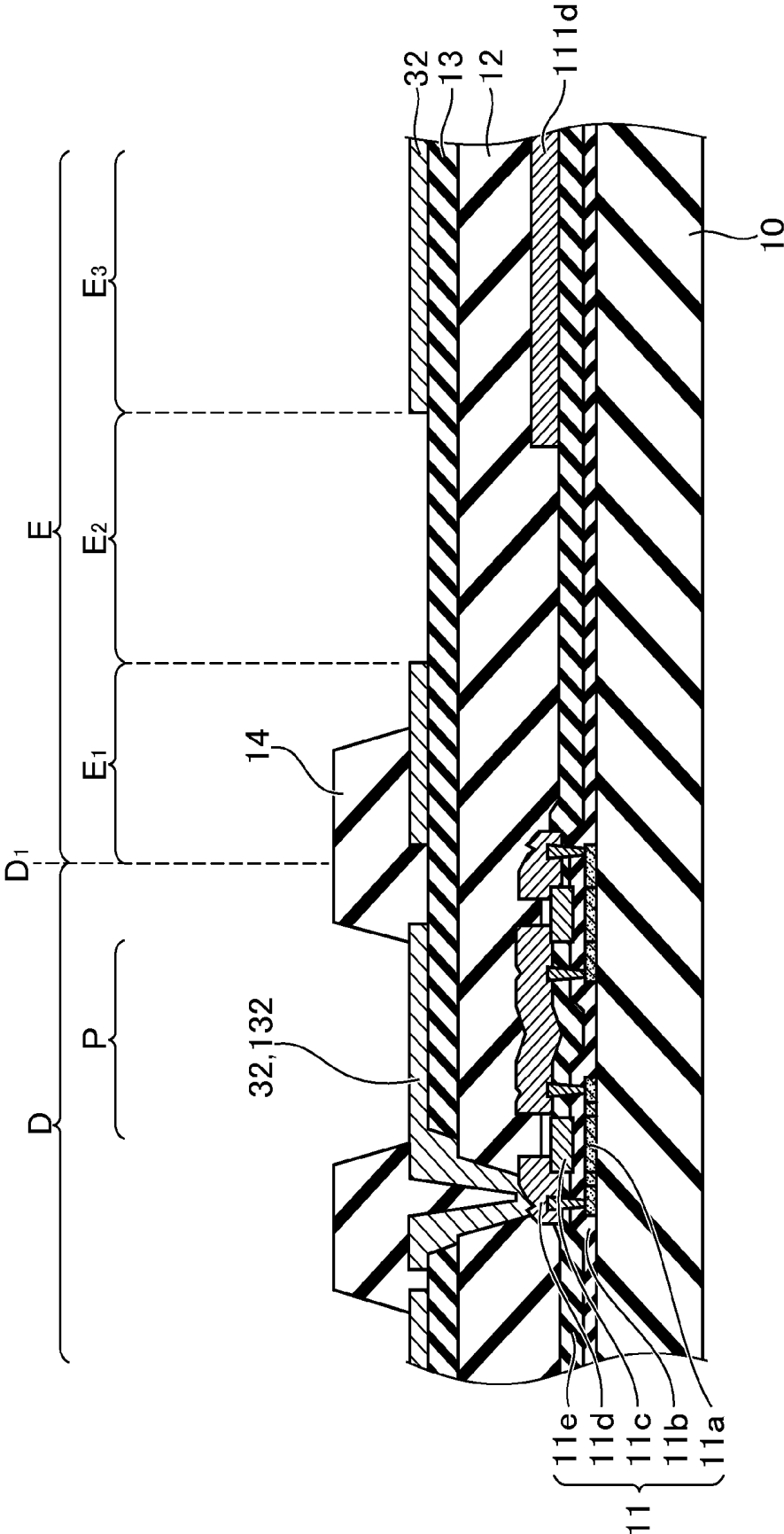


FIG.12

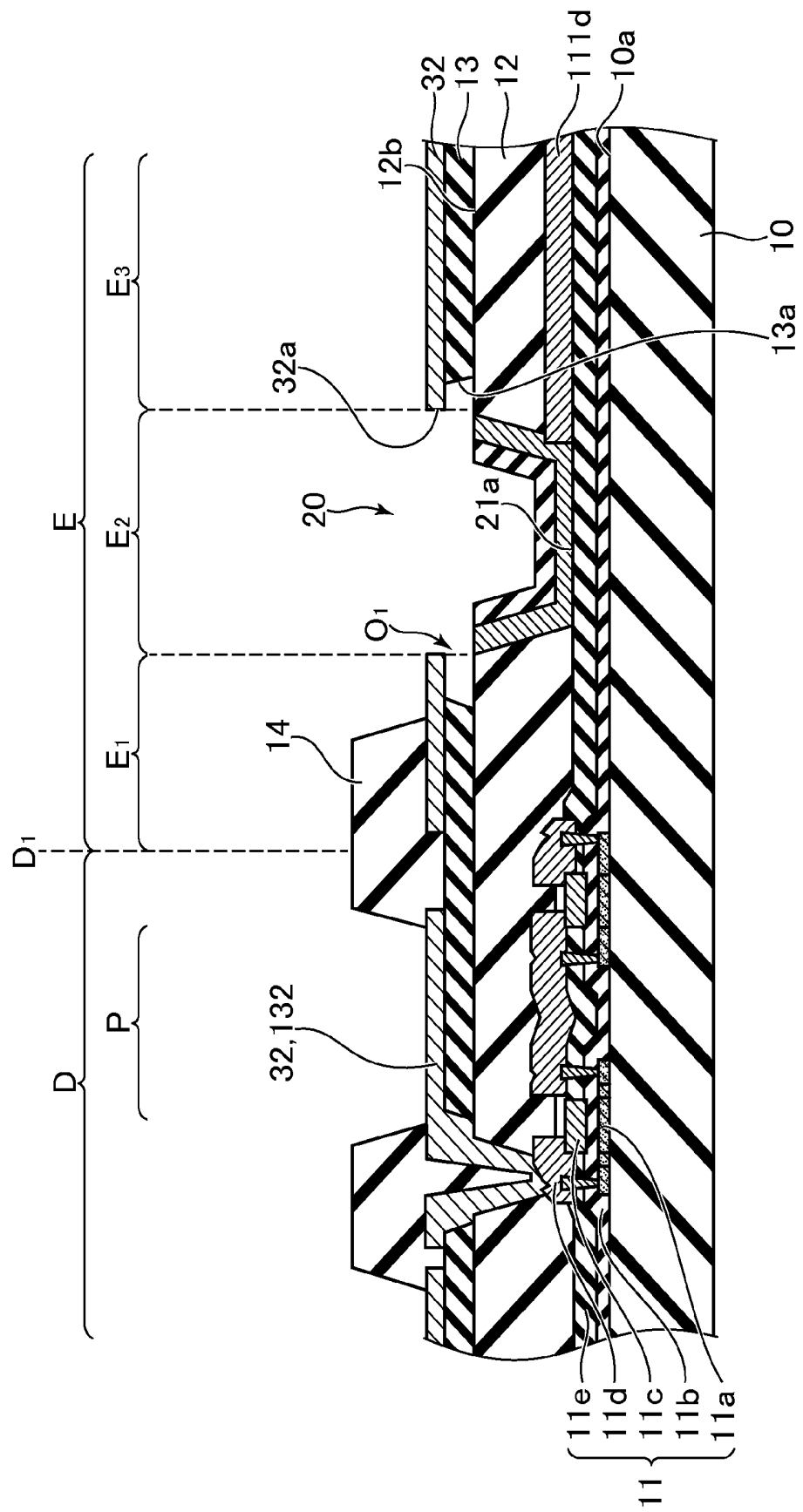


FIG.13

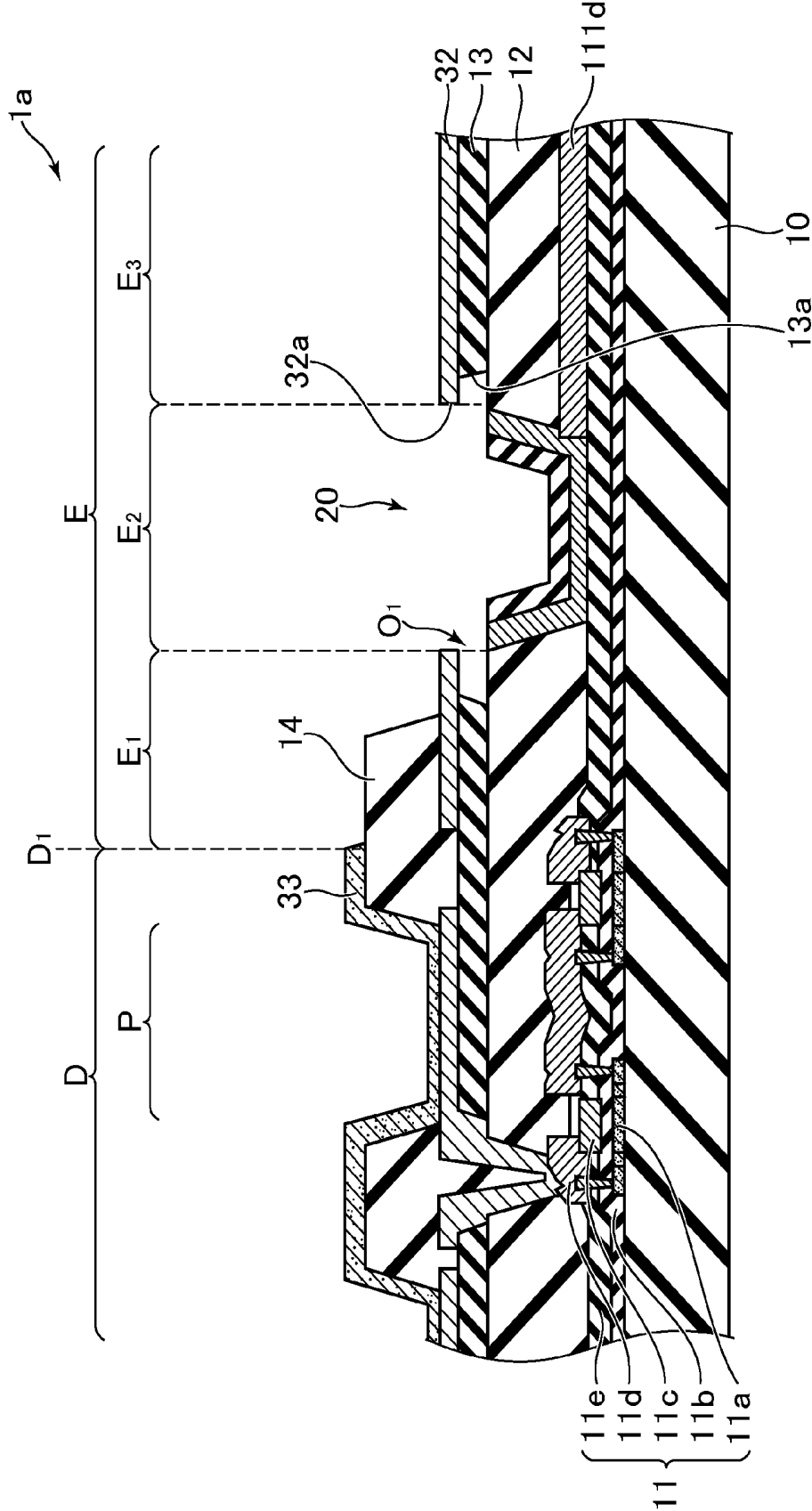


FIG.14

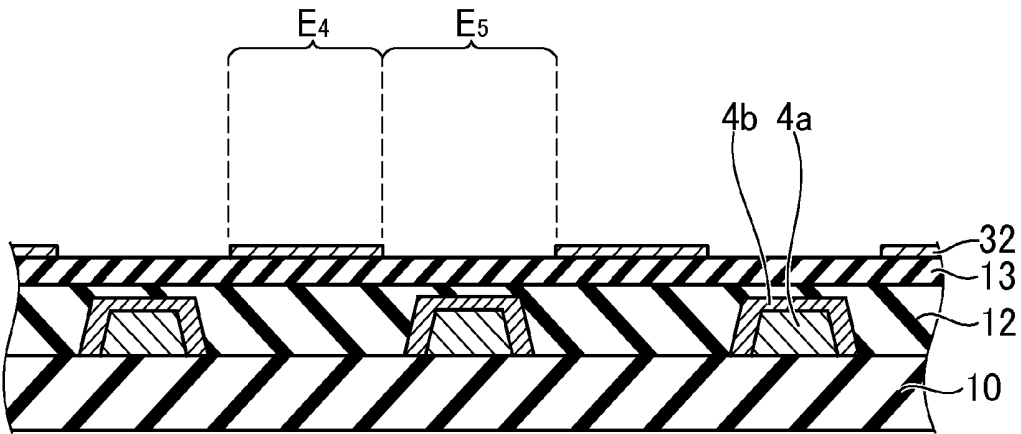


FIG. 15

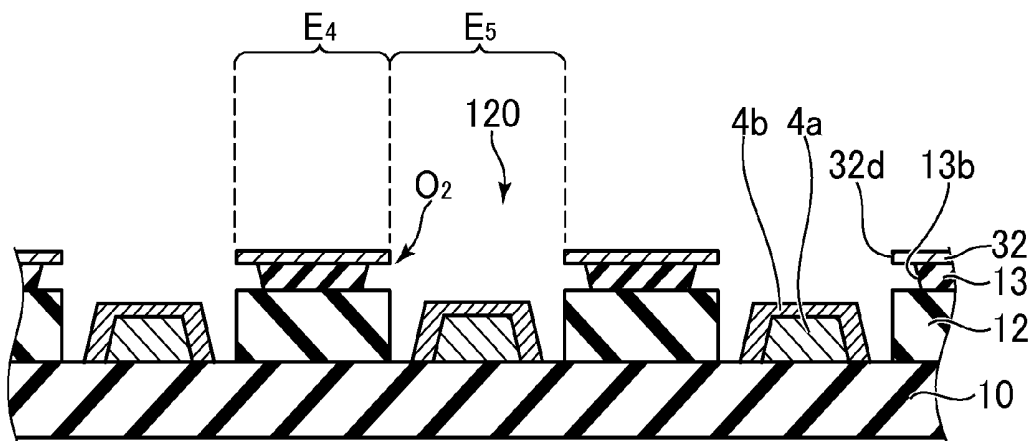
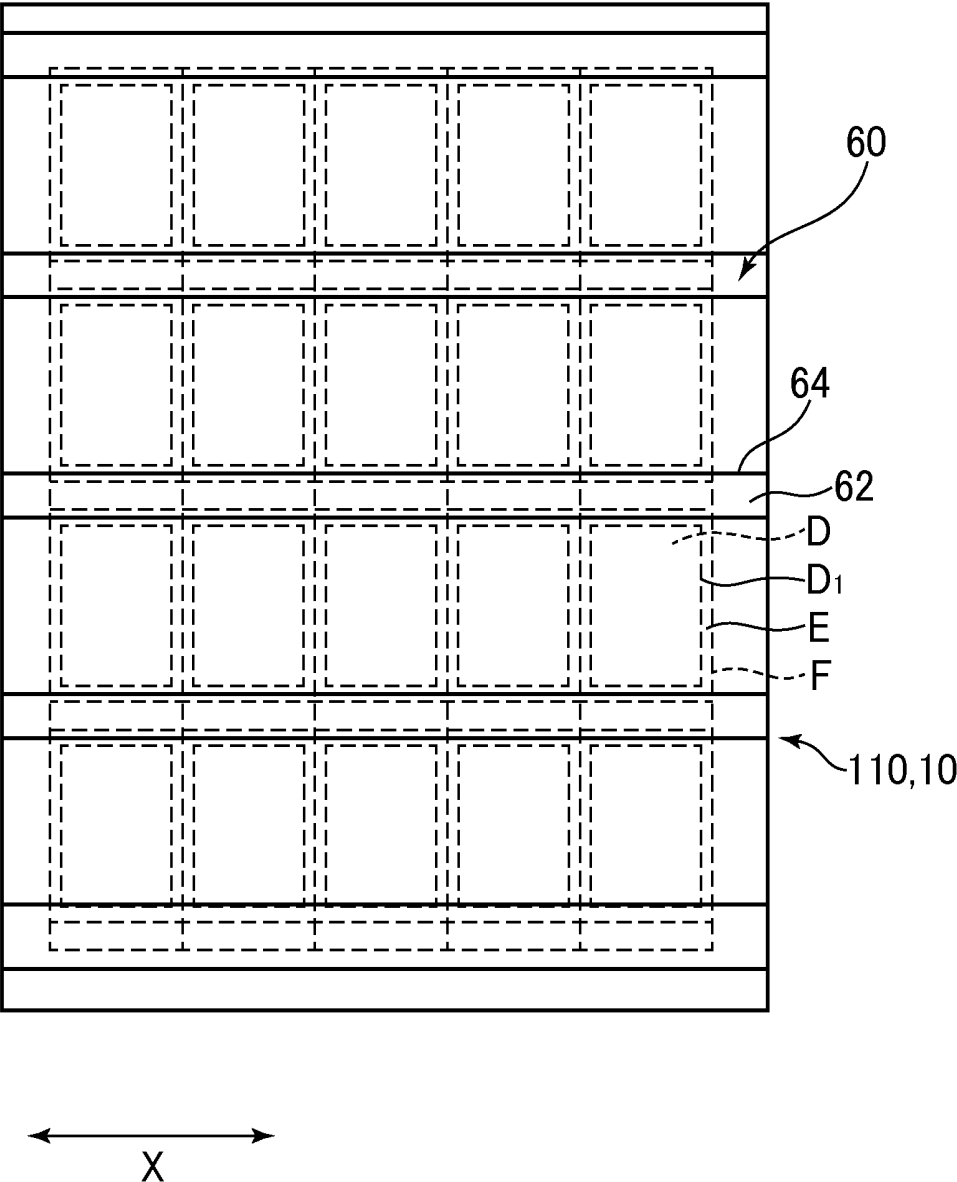


FIG.16



**ORGANIC ELECTROLUMINESCENCE
DISPLAY DEVICE AND METHOD OF
MANUFACTURING ORGANIC
ELECTROLUMINESCENCE DISPLAY
DEVICE**

**CROSS-REFERENCE TO RELATED
APPLICATION**

[0001] The present application claims priority from Japanese application JP 2013-194351 filed on Sep. 19, 2013, the content of which is hereby incorporated by reference into this application.

BACKGROUND OF THE INVENTION

[0002] 1. Field of the Invention

[0003] The present invention relates to an organic electroluminescent display device, and a method of manufacturing the organic electroluminescent display device.

[0004] 2. Description of the Prior Art

[0005] As thin and lightweight displays, an organic electroluminescent display device (hereinafter referred to as “organic EL display device”) using organic electroluminescent elements (hereinafter referred to as “organic EL elements”) has been developed. The organic EL elements each have a structure in which an organic layer having a light emitting layer is sandwiched between a pixel electrode and a counter electrode. Also, in the organic EL display device, a frame area that is an area around a display area in which an image is displayed is required to be narrowed.

[0006] In manufacturing the organic EL display device of this type, a matrix-shaped electrode is formed in the display area with the use of a mask. The mask of this type has openings formed in a matrix, and a shielding portion disposed in a lattice pattern in correspondence with the frame areas. After the electrode has been formed, a substrate is cut along the respective frame areas to form singulated organic EL display devices.

[0007] Also, as another manufacturing method, JP 2004-342455 A discloses a method in which a substrate on which a film has been formed is irradiated with a laser by a manufacturing device added with a laser processing chamber to form a film having a desired pattern.

SUMMARY OF THE INVENTION

[0008] In recent years, the frame area has been required to be narrowed with a reduction in the size of the organic EL display device. However, as a width of the shielding portion of the mask is narrowed more in association with the narrowed frame of the frame area, the mask is easily deformed by a stress in forming a film of the electrode. For that reason, there is a risk that a precision in formation of the electrode pattern may be degraded due to the film formation using the mask.

[0009] Also, according to the above film forming method, the laser processing chamber needs to be added to the conventional manufacturing device. This makes it difficult to suppress the manufacturing costs of the organic EL display device. Also, because a process of laser processing is added in forming the electrode film, the number of processes increases. For that reason, it is difficult to facilitate the formation of the electrode pattern.

[0010] The present invention has been made in view of the above circumstances, and therefore aims at realizing a

method of manufacturing an organic electroluminescent display device that can form an electrode pattern with high precision.

(1) According to the present invention, there is provided a method of manufacturing an organic electroluminescent display device, including the steps of: forming a first insulating layer on a substrate having a rectangular display area and a frame area which surrounds an outer periphery of the display area; forming a first patterning layer on the first insulating layer; forming a second patterning layer on the first patterning layer; removing a part of the second patterning layer and the first patterning layer in the frame area to form a trench portion; and forming an electrode layer on the second patterning layer and in the trench portion, in which in the step of forming the trench portion, an end of the first patterning layer exposed within the trench portion is etched to an outside more than an end of the second patterning layer exposed within the trench portion in a plan view, in which in the step of forming the electrode layer, the electrode layer formed within the trench portion which is located on a lower side of the end of the first patterning layer is isolated from the electrode layer formed outside of the trench portion, which is located on an upper side of the end of the first patterning layer.

(2) According to the present invention, in the method of manufacturing the organic electroluminescent display device according to the item (1), the display area is arrays in a matrix on the substrate, the trench portion is formed along an outer periphery of the display area in the plan view, the frame area is cut along the trench portion after the electrode layer is formed to divide the substrate into a plurality of pieces.

(3) According to the present invention, the method of manufacturing the organic electroluminescent display device according to the item (1) further comprises the step of forming a ground in the frame area of the substrate before the step of forming the first insulating layer, in which in the step of forming the trench portion, the ground is exposed within the trench portion, and in the step of forming the electrode layer, the electrode layer is connected to the ground exposed within the trench portion.

(4) According to the present invention, in the method of manufacturing the organic electroluminescent display device according to the item (1), at least a part of a plurality of the trench portions are aligned at intervals from each other, and in the step of forming the electrode layer, the electrode layer formed in the part of trench portion is isolated from the electrode layer formed between the part of trench portions to form the terminal having the electrode layer within the part of trench portion.

(5) According to the present invention, in the method of manufacturing the organic electroluminescent display device according to the item (1), the second patterning layer is a pixel electrode layer, and the electrode layer is a counter electrode layer facing the pixel electrode layer.

(6) According to the present invention, in the method of manufacturing the organic electroluminescent display device according to the item (1), in the step of forming electrode layer, a material of the electrode layer is deposited on the second patterning layer with the use of a mask having a shielding portion extending in only one direction in correspondence with a part of the frame area to form an area in which the electrode layer is not formed in a part of the frame area.

(7) According to the present invention, there is provided an organic electroluminescent display device including: a sub-

strate having a rectangular display area and a frame area which surrounds an outer periphery of the display area; a first insulating layer that is formed on the substrate; a first patterning layer that is formed on the first insulating layer; a second patterning layer that is formed on the first patterning layer; a trench portion that is formed in the frame area, and from which a part of the second patterning layer and the first patterning layer are removed; and an electrode layer that is formed on the second patterning layer and within the trench portion, in which an end of the first patterning layer exposed within the trench portion is located on an outside of an end of the second patterning layer exposed within the trench portion in a plan view, and the electrode layer that is located on a lower side of the end of the first patterning layer and formed within the trench portion is isolated from the electrode layer located on an upper side of the end of the first patterning layer and formed in a periphery of the trench portion.

[0011] According to the method of manufacturing the organic electroluminescent display device in the present invention, because an arbitrary portion of the electrode layer can be electrically isolated without any mask, a conductive pattern of the electrode layer can be formed with high precision.

BRIEF DESCRIPTION OF THE DRAWINGS

[0012] FIG. 1 is a schematic plan view of an organic EL display device according to an embodiment of the present invention;

[0013] FIG. 2 is a schematic cross-sectional view taken along a line II-II of the organic EL display device illustrated in FIG. 1;

[0014] FIG. 3 is a partially enlarged view of an area III of the organic EL display device illustrated in FIG. 1;

[0015] FIG. 4 is a partially enlarged view of an area IV of the organic EL display device illustrated in FIG. 1;

[0016] FIG. 5 is a schematic cross-sectional view taken along a line V-V illustrated in FIG. 4;

[0017] FIG. 6 is a schematic plan view of an organic EL display device according to a modification of the present invention;

[0018] FIG. 7 is a schematic plan view illustrating a method of manufacturing the organic EL device organic EL display device illustrated in FIG. 1;

[0019] FIG. 8 is a schematic cross-sectional view taken along a line VIII-VIII illustrating the method of manufacturing the organic EL display device illustrated in FIG. 1;

[0020] FIG. 9 is a schematic cross-sectional view taken along the line VIII-VIII illustrating the method of manufacturing the organic EL display device illustrated in FIG. 1;

[0021] FIG. 10 is a schematic cross-sectional view taken along the line VIII-VIII illustrating the method of manufacturing the organic EL display device illustrated in FIG. 1;

[0022] FIG. 11 is a schematic cross-sectional view taken along the line VIII-VIII illustrating the method of manufacturing the organic EL display device illustrated in FIG. 1;

[0023] FIG. 12 is a schematic cross-sectional view taken along the line VIII-VIII illustrating the method of manufacturing the organic EL display device illustrated in FIG. 1;

[0024] FIG. 13 is a schematic cross-sectional view taken along the line VIII-VIII illustrating the method of manufacturing the organic EL display device illustrated in FIG. 1;

[0025] FIG. 14 is a schematic cross-sectional view taken along a line V-V illustrating the method of manufacturing the organic EL display device illustrated in FIG. 1;

[0026] FIG. 15 is a schematic cross-sectional view taken along the line V-V illustrating the method of manufacturing the organic EL display device illustrated in FIG. 1; and

[0027] FIG. 16 is a schematic plan view illustrating a state in which a mask is arranged on a mother substrate illustrating the method of manufacturing the organic EL display device illustrated in FIG. 1.

DETAILED DESCRIPTION OF THE INVENTION

[0028] Hereinafter, a description will be given of an organic EL display device 1a according to an embodiment of the present invention with reference to the accompanying drawings. The drawings referred to in the following description may illustrate an enlarged portion of the features for convenience in order to facilitate understanding of the features, and the size ratio of the respective components is not always identical with a real one. Also, the materials exemplified in the following description are exemplary, and the respective components may be made of materials different from the exemplified materials, and can be implemented with changes without departing from the spirit thereof.

[0029] FIG. 1 is a schematic plan view of an organic EL display device 1a according to an embodiment of the present invention. The organic EL display device 1a includes a substrate 10, a flexible wiring substrate 2, a first terminal 4, and thin film transistors 11, a first insulating layer 12, a first patterning layer 13, organic EL elements 30, and a sealing film 40 which will be described later, and a counter substrate 50.

[0030] The substrate 10 includes a display area D rectangular in a plan view, and a frame area E located to surround an outer periphery D₁ of the display area D.

[0031] A counter substrate 50 is arranged on an upper surface 10a of the substrate 10 so as to face the substrate 10. As illustrated in FIG. 1, the flexible wiring substrate 2 and plural first terminals 4 are disposed in an area where the counter substrate 50 is not arranged on the upper surface 10a of the substrate 10. The flexible wiring substrate 2 is a member for supplying image data to an IC (integrated circuit) chip (not shown) that is connected to the first terminals 4 from an external of the organic EL display device 1a.

[0032] The first terminals 4 are electronic components electrically connected to the flexible wiring substrate 2 or an external device such as an IC chip. In this embodiment, the first terminals 4 are disposed in a connection area of the IC chip not shown and the substrate 10. Also, second terminals 5 having the same configuration as that of the first terminals 4 are disposed in a connection area of the flexible wiring substrate 2 and the substrate 10.

[0033] The plural first terminals 4 and the plural second terminals 5 are each arranged at intervals from each other. The first terminals 4 receive image data from the external, and supply voltage signals to be applied to respective pixels to the organic EL elements 30 to be described later through an IC chip not shown.

[0034] FIG. 2 is a schematic cross-sectional view taken along a line II-II of the organic EL display device illustrated in FIG. 1. FIG. 2 illustrates a cross-section of a neighborhood of a boundary D₁ between the display area D and the frame area E. Hereinafter, for convenience of description, the respective configurations of the display area D and the frame area E will be described in order in detail.

[0035] The display area D is an area in which an image is displayed. The organic EL elements 30 are formed in the

display area D. The thin film transistors **11** are formed on the display area D of the substrate **10**. The first insulating layer **12**, the first patterning layer **13**, the organic EL element **30**, and the sealing film **40** are formed on each of the thin film transistors **11**.

[0036] The thin film transistor **11** drives the organic EL element **30**. The thin film transistor **11** is disposed on the substrate **10** for each of pixels P. The thin film transistor **11** includes a polysilicon semiconductor layer **11a**, a gate insulating layer **11b**, a gate electrode **11c**, a source/drain electrode **11d**, and an interlayer insulating film **11e**.

[0037] The first insulating layer **12** is an insulating layer made of, for example, an organic material. The first insulating layer **12** is disposed to cover the thin film transistor **11**. The first insulating layer **12** in the display area D is disposed between the thin film transistor **11** and the organic EL element **30** to electrically isolate the respective adjacent thin film transistors **11** from each other, and the thin film transistor **11** from the organic EL element **30**. The provision of the first insulating layer **12** on the thin film transistor **11** flattens an area in which the organic EL element **30** to be described later is formed.

[0038] The first patterning layer **13** in the display area D functions as a passivation film. The first patterning layer **13** is made of a material having an insulating property such as SiO₂, SiN, acrylic, or polyimide, and formed to cover the first insulating layer **12**.

[0039] Also, a contact hole **12a** that electrically connects the thin film transistor **11** to the organic EL element **30** is formed in the first patterning layer **13** in the display area D for each of the organic EL elements **30**.

[0040] A reflective film not shown may be formed in an area corresponding to each of the pixels P on the first patterning layer **13**. The reflecting film is disposed to reflect light emitted from the organic EL element **30** toward the counter substrate **50** side. The reflecting film is more preferable as the optical reflectance is higher, and can be formed of a metal film made of aluminum or silver (Ag).

[0041] The plural organic EL elements **30** are formed on the first patterning layer **13** in correspondence with the respective pixels P. The organic EL element **30** includes a pixel electrode layer (second patterning layer) **32**, an organic layer **33** having at least a light emitting layer, and a counter electrode layer (electrode layer) **34** laminated to cover the organic layer **33** to function as a light emitting source.

[0042] The second patterning layer **32** in the display area D functions as a pixel electrode layer that injects a drive current into the organic layer **33**. Hereinafter, the second patterning layer **32** in the display area D is called a pixel electrode layer **132**. The pixel electrode layer **132** is formed in the display area D of the substrate **10** for each of the pixels P. The pixel electrode layer **132** is connected to the first contact hole **12a**. With this configuration, the pixel electrode layer **132** is electrically connected to the thin film transistor **11**, and supplied with a drive current from the thin film transistor **11**.

[0043] The pixel electrode layer **132** (second patterning layer **32**) is made of a material having a conductive property. Specifically, it is preferable that the pixel electrode layer **132** is made of, for example, ITO (indium tin oxide). Alternatively the pixel electrode layer **132** may be made of a material having translucency and conductivity such as IZO (indium zinc oxide composite), tin oxide, zinc oxide, indium oxide, or aluminum oxide composite oxide. The reflecting film is made of metal such as silver, and when the reflecting film is con-

figured to come in contact with the pixel electrode layer **132**, the reflecting film functions as a part of the pixel electrode layer **132**.

[0044] A pixel separation film **14** is formed between the respective pixel electrode layers **132** adjacent to each other along the boundary between the respective pixels P adjacent to each other. The pixel separation film **14** prevents contact of the respective pixel electrode layers **132** adjacent to each other, and a leakage current between the pixel electrode layer **132** and the counter electrode layer **34**. The pixel separation film **14** is made of an insulating material, and specifically made of, for example, a photosensitive resin composition.

[0045] The organic layer **33** is a layer having at least the light emitting layer which is made of an organic material. The organic layer **33** is formed to contact with the pixel electrode layer **32**. The organic layer **33** may be formed for each of the pixels P. Also, the organic layer **33** may be formed to cover an overall surface of the area in which the pixels P are arranged in the display area D. The organic layer **33** has a layer that emits light, and the emitted light may be white or other colors.

[0046] In the organic layer **33** is configured by laminating a hole injection layer, a hole transport layer, a light emitting layer, an electron transport layer, and an electronic injection layer, not shown, for example, in order from the pixel electrode layer **32** side. A laminate structure of the organic layer **33** is not limited to this example, but the laminate structure is not specified if at least the light emitting layer is included.

[0047] The light emitting layer is made of an organic electroluminescent material that emits light by coupling holes with electrons. The organic electroluminescent material of this type which is generally used, for example, as an organic light emitting material may be used.

[0048] The counter electrode layer **34** is formed to cover the organic layer **33** in the overall display area D. With the provision of this configuration, the counter electrode layer **34** contacts in common to the organic layers **33** of the plural organic EL elements **30** in the display area D.

[0049] The counter electrode layer **34** is made of a material having translucency and conductivity. Specifically, it is preferable that the counter electrode layer **34** is made of, for example, ITO. Alternatively, the pixel counter electrode layer **34** may be made of a conductive metal oxide such as ITO or InZnO mixed with metal such as silver or magnesium, or a laminate of a metal thin film made of silver or magnesium and a conductive material oxide.

[0050] An upper surface of the counter electrode layer **34** is covered with a transparent sealing film **40** made of an insulating material over the plural pixels P. The sealing film **40** covers the overall substrate **10** to prevent moisture from penetrating into the respective layers including the organic layer **33**.

[0051] An upper surface of the sealing film **40** is covered with the counter substrate **50** through a filler **45** made of, for example, an inorganic material. The counter substrate **50** is arranged to face the substrate **10**. The counter substrate **50** is formed of, for example, an insulating substrate, and a configuration of the counter substrate **50** is not particularly restricted.

[0052] Subsequently, a description will be given of a configuration of the organic EL display device **1a** in the frame area E. As illustrated in FIGS. **1** and **2**, the frame area E represents an area around the outer periphery D₁ of the dis-

play area D. Hereinafter, for convenience of the description, the outer periphery of the frame area E is called “outer periphery F”.

[0053] The frame area E is different from the display area D at least in that the organic EL element 30 is not formed, and a trench portion (first trench portion) 20 is formed. Hereinafter, it is assumed that an area closer to the display area D side than the first trench portion 20 is called “auxiliary area E₁”, an area in which the first trench portion 20 is formed is called “first trench area E₂”, and an area on the outer periphery F side in the area around the first trench area E₂ is called “first peripheral area E₃”.

[0054] The auxiliary area E₁ is an area between the display area D and the first trench area E₂. With the provision of the auxiliary area E₁, a step between the display area D and the first trench area E₂ is eliminated.

[0055] In the auxiliary area E₁, on the substrate 10 are laminated the gate insulating layer 11b, the interlayer insulating film 11e, the first insulating layer 12, the first patterning layer 13, the pixel separation film 14, the second patterning layer 32, the electrode layer (counter electrode layer) 34, and the sealing film 40 on each other in the stated order. An end of the organic layer 33 is located between the outer periphery D₁ of the display area D, and a boundary of the auxiliary area E₁ and the first trench area E₂.

[0056] Then, the first peripheral area E₃ will be described. For convenience of the description, a configuration of the first trench area E₂ will be described later. The first peripheral area E₃ is an area electrically isolated from the display area D. The first peripheral area E₃ is different from the auxiliary area E₁ in that the pixel separation film 14 is not formed between the first patterning layer 13 and the second patterning layer 32.

[0057] Subsequently, the first trench area E₂ will be described. The first trench portion 20 is provided for forming a first overhang structure O₁ to be described later as well as an electrode pattern. The first trench area E₂ is formed, for example, along the outer periphery D₁ of the display area D. A portion where the first trench portion 20 is formed is not limited to the above example. The first trench area E₂ may be disposed along only two opposed sides in a plan view in the outer periphery D₁ rectangular in the plan view.

[0058] In the first trench area E₂, the gate insulating layer 11b and the interlayer insulating film 11e are laminated, for example, on the substrate 10. The upper surface of the interlayer insulating film 11e forms a bottom surface 21a of the first trench portion 20. Also, the electrode layer 34 and the sealing film 40 are laminated on the bottom surface 21a.

[0059] The first trench portion 20 is formed by removing a part of at least the electrode layer 34, the second patterning layer 32, and the first patterning layer 13. A depth of the first trench portion 20 in a thickness direction of the substrate 10 is not particularly restricted, but a height from the upper surface 10a of the substrate 10 to the bottom surface 21a has only to be lower than at least a height from the upper surface 10a to an upper surface 12b of the first insulating layer 12. The first trench portion 20 according to the first embodiment is obtained by, for example, removing the electrode layer 34, the second patterning layer 32, the first patterning layer 13, and the first insulating layer 12.

[0060] Also, it is preferable that a ground 111d is exposed to the bottom surface 21a of the first trench portion 20. The ground 111d is provided to keep a constant potential of the electrode layer 34 formed within the first trench portion 20. The ground 111d is connected to the electrode layer 34 and

the line not shown in the first trench portion 20. The ground 111d according to this embodiment is made of, for example, the same material as that of the source/drain electrode 11d in the display area D, and formed in the same layer. However, the configuration of the ground 111d is not particularly restricted.

[0061] Then, the overhang structure (first overhang structure) O₁ within the first trench portion 20 will be described. The first overhang structure O₁ is a structure to electrically isolate the electrode layer 34 in the display area D from the electrode layer 34 (electrode film 334) in the first peripheral area E₃. Also, the first overhang structure O₁ is a uneven structure formed by an end 13a of the first patterning layer 13, and an end 32a of the second patterning layer 32.

[0062] With the formation of the first overhang structure O₁, the electrode layer 34 (electrode film 134) formed in the auxiliary area E₁ is divided from the electrode layer 34 (electrode film 234) formed in the first trench area E₂. With this configuration, the electrode layer 34 in the display area D and the electrode film 134 in the auxiliary area E₁ are electrically isolated from the electrode film 234 in the first trench area E₂.

[0063] Likewise, the electrode film 234 in the first trench area E₂ and the electrode layer 34 (electrode film 334) formed in the first peripheral area E₃ are divided from each other due to the first overhang structure O₁. For that reason, the electrode film 334 in the first peripheral area E₃ is electrically isolated from the electrode film 234 in the first trench area E₂.

[0064] FIG. 3 is a partially enlarged view of an area III of the organic EL display device illustrated in FIG. 1. For convenience of the description, in FIG. 3, the counter substrate 50, the filler 45, and the sealing film 40 are omitted from illustration. As illustrated in FIGS. 2 and 3, the end 13a of the first patterning layer 13 exposed within the first trench portion 20 is located outside of the end 32a of the second patterning layer 32 in a plan view. For that reason, the end 13a of the first patterning layer 13 does not come in contact with the electrode layer 34.

[0065] With the above configuration, the electrode layer 34 (electrode film 234) formed within the first trench portion 20 (first trench area E₂) which is located on a lower side of the end 13a of the first patterning layer 13 is isolated from the electrode layer 34 (electrode films 134, 334) formed in the periphery (auxiliary area E₁ and first peripheral area E₃) of the first trench portion 20 which is located on an upper side of the end 13a of the first patterning layer 13. In this embodiment, “upper side” represents a direction of the counter substrate 50 side when viewed from the substrate 10, and “lower side” represents a direction of the substrate 10 side when viewed from the counter substrate 50.

[0066] With the provision of the above configuration, the electrode layer 34 (electrode film 234) formed in the first trench area E₂ is electrically isolated from the electrode layer 34 formed in the display area D and the auxiliary area E₁. Also, with this configuration, the electrode layer 34 in the display area D is electrically isolated from the electrode layer 34 (electrode film 334) in the first peripheral area E₃.

[0067] The end 13a of the first patterning layer 13 has only to be located outside of at least the end 32a of the second patterning layer 32 in the plan view. As illustrated in FIG. 2, the end 13a of the first patterning layer 13 is located outside of an inner peripheral surface 21 of the first trench portion 20 in the plan view. With the provision of this configuration, as compared with the organic EL display device without the

provision of this configuration, the electrode layer **34** is more surely isolated (divided) through the first overhang structure O_1 therebetween.

[0068] In the organic EL display device **1a** according to this embodiment, the second patterning layer (pixel electrode layer) **32** and the electrode layer (counter electrode layer) **34** is isolated (divided) on a portion where the first overhang structure O_1 is formed. For that reason, as compared with the conventional organic EL display device having the electrode layer formed with the use of the mask, an improvement in the precision and miniaturization of the pattern of the electrode layer **34** can be realized.

[0069] Also, because a current path in the electrode layer **34** is divided through the first overhang structure O_1 therebetween, an improvement in the precision of the pattern of the divided portion of the current path is also improved. For that reason, the narrowing and an improvement in the reliability of the organic EL display device **1a** can be realized.

[0070] Also, in the organic EL display device **1a** according to this embodiment, the first insulating layer **12** and the organic layer **33** each made of organic material are not formed in the first trench area E_2 . With this configuration, as compared with the organic EL display device without the provision of this configuration, even if moisture penetrates from the first peripheral area E_3 side, moisture is prevented from penetrating in the first trench area E_2 . For that reason, the moisture diffusion toward the display area D side can be prevented.

[0071] The portion in which the overhang structure is formed is not limited to the above example, but may be formed to surround the first terminals **4** and the second terminals **5**. FIG. **4** is a partially enlarged view of an area IV of the organic EL display device **1a** illustrated in FIG. **1**, and FIG. **5** is a schematic cross-sectional view taken along a line V-V illustrated in FIG. **4**. Hereinafter, the area around the first terminals **4** will be described in detail.

[0072] The respective first terminals **4** are formed in plural trench portions (second trench portions) **120** aligned at intervals from each other. The second trench portions **120** are trenches provided for configuring a second overhang structure O_2 which will be described later. Hereinafter, for convenience of the description, it is assumed that an area around the second trench portions **120** is called "second peripheral area E_4 ", and an area in which the second trench portions **120** are formed is called "second trench area E_5 ".

[0073] In the second peripheral area E_4 , the first insulating layer **12**, the first patterning layer **13**, the second patterning layer **32**, and the electrode layer **34** are laminated on the substrate **10** in the stated order.

[0074] The second trench portions **120** in the second trench area E_5 is grooves provided for configuring the second overhang structure O_2 which will be described later. The second trench area E_5 is obtained by removing, for example, the second patterning layer **32**, the first patterning layer **13**, and the first insulating layer **12**, and the substrate **10** is exposed to the bottom surface thereof.

[0075] The first terminals **4** and the second overhang structure O_2 are formed within the second trench portions **120**. The first terminals **4** include, for example, a wiring layer **4a**, a first terminal electrode **4b** that covers the first terminals **4**, and a second terminal electrode layer **34c** that covers the first terminal electrode **4b**.

[0076] The wiring layer **4a** is made of metal such as aluminum. The wiring layer **4a** is a layer forming a base material of

the first terminals **4**. The first terminal electrode **4b** is made of, for example, ITO. Also, the second terminal electrode layer **34c** is formed in the same layer as that of the electrode layer **34** in the display area D. The first terminal electrode **4b** and the second terminal electrode layer **34c** are laminated on the wiring layer **4a** so as to be electrically connected to the wiring layer **4a**. With this configuration, the wiring layer **4a** is electrically connected to an IC chip **3** through the first terminal electrode **4b** and the second terminal electrode layer **34c**.

[0077] The second overhang structure O_2 is a uneven structure for electrically separating the second terminal electrode layer **34c** in the second trench area E_5 from the electrode layer **34** in the second peripheral area E_4 . The second overhang structure O_2 includes an end **13b** of the first patterning layer **13**, and an end **32d** of the second patterning layer **32**.

[0078] As illustrated in FIGS. **4** and **5**, the end **13b** of the first patterning layer **13** exposed within the second trench portions **120** is located outside of the end **32d** of the second patterning layer **32** exposed within the second trench portions **120** in the plan view. With the provision of the above configuration, the end **13b** of the first patterning layer **13** is prevented from being covered with the electrode layer **34** covering the second patterning layer **32** in the second peripheral area E_4 . For that reason, the end **13b** of the first patterning layer **13** is exposed within the second trench portion **120**.

[0079] As described above, the end **13b** of the first patterning layer **13** is formed outside of the end **32d** of the second patterning layer **32** in the plan view. With this configuration, the electrode layer **34** (second terminal electrode layer **34c**) formed within the second trench portions **120** (second trench area E_5) which is located on a lower side of the end **13b** of the first patterning layer **13** is isolated from the electrode layer **34** formed in the periphery (second peripheral area E_4) of the second trench portions **120**, which is located on an upper side of the end **13b** of the first patterning layer **13**.

[0080] With the provision of the above configuration, the electrode layer **34** (second terminal electrode layer **34c**) formed within the second trench portions **120** (second trench area E_5) is electrically isolated from the electrode layer **34** formed in the second peripheral area E_4 .

[0081] In the organic EL display device **1a** according to this embodiment, with the provision of this configuration, the second overhang structure O_2 is formed with high precision. For that reason, even the fine first terminals **4** can be electrically isolated from the electrode layer **34** in the second peripheral area E_4 .

[0082] The organic EL display device **1a** according to this embodiment of the present invention has been described above. However, the present invention is not limited to the above embodiment. For example, the portions in which the first overhang structure O_1 and the second overhang structure O_2 are formed are not limited to the above example, but a portion in which the electrode layer **34** is to be electrically isolated may be appropriately selected.

[0083] Also, the ground may be formed other than the portion in which the first overhang structure O_1 is formed. FIG. **6** is a schematic plan view of an organic EL display device **1b** according to a modification of the present invention. The organic EL display device **1b** includes a conductive layer contact point (ground) **134d**, a metal frame **136**, and a conductive tape **138** in addition to the above organic EL display device **1a**.

[0084] The conductive layer contact point **134d** is electrically connected to the metal frame **136** through the conduc-

tive tape **138**. The conductive layer contact point **134d** is connected to the metal frame **136** to function as the ground. The metal frame **136** is a frame that supports the organic EL display device **1b**.

[0085] With the provision of the above configuration, the potential of the electrode layer **34** in the frame area E is kept constant. Also, heat is diffused into the metal frame **136** from the electrode layer **34** through the conductive tape **138**, as result of which as compared with the organic EL display device without the provision of this configuration, thermal storage of the electrode layer **34** is suppressed. For that reason, the reliability of the organic EL display device **1b** can be improved.

[0086] Then, a description will be given of a method of manufacturing the organic EL display device **1a** according to the embodiment of the present invention with reference to the accompanying drawings.

[0087] The method of manufacturing the organic EL display device **1a** according to this embodiment includes the steps of forming the wiring layer **4a** on the frame area E on the substrate **10**, forming the thin film transistor **11** in the display area D, forming the first insulating layer **12** on the thin film transistor **11**, forming the first patterning layer **13** on the first insulating layer **12**, forming the second patterning layer **32** on the first patterning layer **13**, forming the first trench portion **20**, and forming the organic EL element **30**.

[0088] FIG. 7 is a schematic plan view illustrating a method of manufacturing the organic EL display device **1a** illustrated in FIG. 1. First of all, an insulating substrate (mother substrate) **110** is prepared. The mother substrate **110** corresponds to plural substrates **10** continuous to each other. Also, in each of areas forming the substrates **10** in the mother substrate **110** are provided the rectangular display area D and the frame area E surrounding the outer periphery D₁ of each the display area D. The outer periphery F of the frame area E corresponds to a cut line L. The mother substrate **110** is cut along the cut line L to be singulated into plural substrates **10**. Then, the wiring layer **4a** is formed in the frame area E, and details of this process will be described later for convenience of the description.

[0089] FIG. 8 is a schematic cross-sectional view taken along a line VIII-VIII illustrating a method of manufacturing the organic EL display device **1a** illustrated in FIG. 1. The cut line VIII-VIII corresponds to the cut line II-II in FIG. 1.

[0090] Then, in the display area D of the area (substrate **10**) corresponding to the substrate **10** of the mother substrate **110**, the polysilicon semiconductor layer **11a**, the gate insulating layer **11b**, a layer of the gate electrode **11c**, a layer of the source/drain electrode **11d**, and the interlayer insulating film **11e** are laminated, and patterned. With this processing, the thin film transistor **11** is formed for each of the pixels P.

[0091] Also, in the above processes, in the frame area E, the gate insulating layer **11b**, the layer of the source/drain electrode **11d**, and the interlayer insulating film **11e** are laminated on each other to form the ground **111d** in the same layer as the source/drain electrode **11d**.

[0092] Then, the first insulating layer **12** made of, for example, an organic material is formed to cover the thin film transistor **11** in the display area D, and the frame area E.

[0093] FIG. 9 is a schematic cross-sectional view taken along the line VIII-VIII illustrating the method of manufacturing the organic EL display device **1a** illustrated in FIG. 1. Then, the first patterning layer **13** made of an insulating

material such as SiO₂ or SiN is laminated to cover the first insulating layer **12** over the display area D and the frame area E.

[0094] Then, the first contact hole **12a** that penetrates through the first patterning layer **13** and the first insulating layer **12**, which is connected to the thin film transistor **11**, is formed for each of the pixels P. Thereafter, the reflecting film not shown which is formed of a metal film may be formed in areas corresponding to the respective pixels P on the first patterning layer **13**.

[0095] Then, the organic EL element **30** is formed in areas corresponding to the respective pixels P over the first patterning layer **13**. A process of forming the organic EL element **30** includes a process of forming the second patterning layer **32** (pixel electrode layer **132**) over the first patterning layer **13**, a process of forming the organic layer **33** having at least a light emitting layer on the second patterning layer **32**, and a process of forming the electrode layer (opposed electrode layer) **34**.

[0096] First, the second patterning layer **32** is formed to cover the first patterning layer **13**. The second patterning layer **32** is made of a material having translucency and conductivity such as ITO. Hereinafter, the second patterning layer **32** formed in the display area D serves as the pixel electrode layer **132**.

[0097] With the formation of the pixel electrode layer **132** for each of the pixels P, the pixel electrode layer **132** is electrically connected to the thin film transistor **11** through the contact hole **12a**. When the pixel electrode layer **132** is formed to come in contact with an upper surface of the reflecting film made of metal, the reflecting film serves as a part of the pixel electrode layer **132**.

[0098] FIG. 10 is a schematic cross-sectional view taken along the line VIII-VIII illustrating the method of manufacturing the organic EL display device **1a** illustrated in FIG. 1. The pixel separation film **14** is formed along a boundary around the adjacent pixels P. The pixel separation film **14** may be used as the second patterning layer **32**.

[0099] FIG. 11 is a schematic cross-sectional view taken along the line VIII-VIII illustrating the method of manufacturing the organic EL display device illustrated in FIG. 1. Then, the trench portion (first trench portion) **20** is formed in the frame area E along the outer periphery D₁ of the display area D, for example, in the plan view.

[0100] The process of forming the first trench portion **20** includes a process of removing a part of the second patterning layer **32** in the frame area E, and a process of removing a part of the first patterning layer **13** and a part of the first insulating layer **12** by etching with the second patterning layer **32** as a mask.

[0101] First, as illustrated in FIG. 11, a part of the second patterning layer **32** in the frame area E is removed. For convenience of the description, it is assumed that the area of the frame area E in which the second patterning layer **32** is removed is the first trench area E₂, an area closer to the display area D than the first trench portion **20** is the auxiliary area E₁, and the area on the outer periphery F side in the area around the first trench area E₂ is the first peripheral area E₃. In this embodiment, the first trench area E₂ is formed along the outer periphery D₁ of the display area D, and the cut line L.

[0102] FIG. 12 is a schematic cross-sectional view taken along the line VIII-VIII illustrating the method of manufacturing the organic EL display device **1a** illustrated in FIG. 1. Then, etching is conducted with the second patterning layer

32 as a mask. As a result, the first trench portion 20 extending along the outer periphery D_1 of the display area D and the cut line L is formed.

[0103] In the formation of the first trench portion 20, the etching conditions may be adjusted so that a height from the upper surface 10a of the substrate 10 to the bottom surface 21a of the first trench portion 20 becomes lower than a height from the upper surface 10a to the upper surface 12b of the first insulating layer 12. In this embodiment, for example, the first patterning layer 13 and the first insulating layer 12 in the first trench area E_2 are removed to expose the interlayer insulating film 11e and the ground 111d to the bottom surface 21a of the trench portion 20.

[0104] Also, in this etching, the etching conditions are adjusted so that the end 13a of the first patterning layer 13 exposed within the trench portion 20 is located outside of the end 32a of the second patterning layer 32 exposed within the trench portion 20 in the plan view. Specifically, for example, the first patterning layer 13 is made of a material lower in etching rate than the second patterning layer 32. Also, the etching may be dry etching or wet etching, and the manner is not restricted.

[0105] The etching is conducted under the above conditions, to thereby remove the first patterning layer 13 more than the second patterning layer 32. With this configuration, the first overhang structure O_1 that is the uneven structure formed by the end 13a of the first patterning layer 13 and the end 32a of the second patterning layer 32 is formed.

[0106] FIG. 13 is a schematic cross-sectional view taken along the line VIII-VIII illustrating the method of manufacturing the organic EL display device 1a illustrated in FIG. 1. The organic layer 33 having the light emitting layer is formed to cover the display area D. Specifically, for example, the organic layer 33 is configured by laminating a hole injection layer, a hole transport layer, a light emitting layer, an electron transport layer, and an electronic injection layer, not shown, for example, in order from the pixel electrode layer 32.

[0107] Then, as illustrated in FIG. 2, a translucent conductive material such as ITO is deposited on the display area D and the frame area E to form the electrode layer 34. As a result, the electrode layer 34 formed on the display area D functions as a counter electrode layer facing the second patterning layer 32. With the above configuration, the organic EL element 30 is formed in the display area D.

[0108] Also, due to the deposition of the conductive material, the electrode layer 34 is formed to cover the second patterning layer 32 and the first trench portion 20 in the frame area E. In the frame area E, with the formation of the first overhang structure O_1 , the electrode layer 34 (electrode film 134) formed in the auxiliary area E_1 is divided from the electrode layer 34 (electrode film 234) formed in the first trench area E_2 .

[0109] Also, the electrode film 234 in the first trench area E_2 and the electrode layer 34 (electrode film 334) formed in the first peripheral area E_3 are divided from each other. The electrode layer 34 formed within the first trench portion 20 which is located on the lower side of the end 13a of the first patterning layer 13 is divided from the electrode layer 34 formed on the second patterning layer 32 in the auxiliary area E_1 , which is located on the upper side of the end 13a.

[0110] Also, in the process of forming the electrode layer 34, the ground 111d exposed within the first trench portion 20 is covered with the electrode layer 34. As a result, the ground 111d is electrically connected to the electrode layer 34.

[0111] Then, the sealing film 40 is formed to cover the display area D and the frame area E. Then, the counter substrate 50 is arranged on the sealing film 40 through the filler 45. Then, the cut line L of the frame area E is cut along the first trench portion 20 to be singulated into the respective substrates 10. With the above processing, the organic EL display device 1a illustrated in FIG. 1 is formed.

[0112] According to the method of manufacturing the organic EL display device 1a in this embodiment, with the formation of the first overhang structure O_1 , the electrode layer 34 can be isolated according to the portion in which the first overhang structure O_1 is formed without using the mask. Also, because the first overhang structure O_1 is formed through photolithography, as compared with the method of manufacturing the organic EL display device using the mask, the conductive pattern of the electrode layer 34 can be formed with high precision.

[0113] Also, because the pattern of the electrode layer 34 can be formed with high precision, as compared with the manufacturing method without the above configuration, the organic EL display device 1a that is reduced in size and narrow in frame can be manufactured.

[0114] Also because the electrode layer 34 can be patterned without using the mask, a reduction in the formation precision of the pattern of the electrode due to the deformation of the mask is not generated. For that reason, as compared with the manufacturing method with the use of the mask, the yield can be improved. Also, because of no use of the mask, the process can be simplified.

[0115] Also, in this embodiment, because the pixel electrode layer is used as the second patterning layer 32, the electrode layer 34 can be separated at an arbitrary portion without increasing the number of processes.

[0116] Also, in this embodiment, since the frame area E is cut along the trench portion 20, the substrate 10 can be singulated along the separation portions of the electrode layer 34. For that reason, as compared with the method of forming the pattern of the electrode layer 34 with the use of the mask, the yield can be improved.

[0117] Also, in this embodiment, since the electrode layer 34 formed within the first trench portion 20 is connected to the ground 111, the potential of the electrode layer 34 formed within the first trench portion 20 can be kept constant.

[0118] In this embodiment, till the process of forming electrode layer 34 in the display area D, the first terminals 4 having the electrode layer 34 is formed in the frame area E. FIG. 14 is a schematic cross-sectional view taken along a line V-V illustrating the method of manufacturing the organic EL display device illustrated in FIG. 1.

[0119] Specifically, for example, first, in the process of forming the wiring layers 4a, the wiring layers 4a extend at intervals from each other in the portion where the first terminals 4 are formed in the frame area E. Then, the first terminal electrode 4b made of a translucent conductive material such as ITO is formed to cover the wiring layer 4a.

[0120] Then, in the process of removing a part of the second patterning layer 32 in the frame area E illustrated in FIG. 11, as illustrated in FIG. 14, the second patterning layer 32 in an area corresponding to the wiring layer 4a is removed by, for example, etching. Hereinafter, for convenience of the description, it is assumed that the area in which the second patterning layer 32 has been removed by etching is the second trench area E_5 , and the area between the second trench areas E_5 adjacent to each other is the second peripheral area E_4 .

[0121] FIG. 15 is a schematic cross-sectional view taken along the line V-V illustrating the method of manufacturing the organic EL display device illustrated in FIG. 1. Then, in the process of forming the first trench portion 20 illustrated in FIG. 12, as illustrated in FIG. 14, the first terminal electrode 4b is exposed by etching with the second patterning layer 32 in the second peripheral area E₄ as the mask. With this processing, the plural trench portions (second trench portions) 120 aligned at spaces from each other are formed in the second trench area E₅.

[0122] In the formation of the second trench portions 120, the etching condition is adjusted so as to remove the first patterning layer 13 more than the second patterning layer 32. With this configuration, the end 13b of the first patterning layer 13 exposed within the second trench portions 120 is located outside of the end 32d of the second patterning layer 32 exposed within the second trench portions 120 in the plan view. With this configuration, the overhang structure O₂ that is the uneven structure formed by the end 13b of the first patterning layer 13 and the end 32d of the second patterning layer 32 is formed.

[0123] Then, in the process of forming the electrode layer 34 so as to cover the display area D and the frame area E illustrated in FIG. 2, as illustrated in FIG. 5, the electrode layer 34 is formed to cover the second peripheral area E₄ and the second trench area E₅. In this situation, since the overhang structure O₂ is formed within the second trench portions 120, the electrode layer 34 is formed to cover the second patterning layer 32 in the second peripheral area E₄ and the terminal electrode 4b in the second trench area E₅ without covering the end 13b of the first patterning layer 13.

[0124] With the above configuration, the electrode layer 34 (second terminal electrode layer 34c) formed within the second trench portions 120 in the second trench area E₅, which is located on the lower side of the end 13b of the first patterning layer 13 is isolated from the electrode layer 34 formed on the second patterning layer 32 in the second peripheral area E₄, which is located on the upper side of the end 13b.

[0125] With the above configuration, the first terminals 4 electrically isolated from the electrode layer 34 in the second peripheral area E₄ is formed within the second trench portions 120.

[0126] In the method of manufacturing the organic EL display device 1a according to this embodiment, as compared with the method of manufacturing the organic EL display device without the provision of this configuration, the conductive pattern of the electrode layer 34 can be formed with high precision. For that reason, the first terminals 4 can be formed with a precise pattern.

[0127] The embodiments of the present invention has been described above. However, the present invention is not limited to the above embodiments. For example, the configuration described in the above-mentioned embodiment may be replaced with substantially the same configuration, the configuration having the same advantages, or the configuration that can achieve the same purpose.

[0128] For example in the process of forming the electrode layer 34, only a part of the electrode layer 34 may be patterned with a mask. FIG. 16 is a schematic plan view illustrating a state in which a mask 60 is arranged on the mother substrate 110 illustrating the method of manufacturing the organic EL display device 1a illustrated in FIG. 1.

[0129] Specifically, for example, in the process of forming the electrode layer 34, a material of the electrode layer 34 is

deposited on the second patterning layer 32 with the use of the mask 60 having a shielding portion 62 extending only in one direction X in correspondence with the part of the frame area E, and openings 64 opened over the plural display areas D. In this embodiment, the shielding portion 62 is arranged in correspondence with the area in which the first terminals 4 are formed. With this configuration, an area in which the electrode layer 34 is not formed is formed in a part of the frame area E (formation area of the first terminals 4).

[0130] In the method of manufacturing the organic EL display device 1a according to this embodiment, because the electrode layer 34 is formed with the use of the mask 60 allowing the shielding portion 62 to extend in only one direction X, as compared with the method using a lattice-shaped mask, the deformation of the mask 60 is suppressed. For that reason, even if the width of the frame area E is reduced, a deterioration of the precision in the pattern of the electrode layer 34 can be prevented.

[0131] While there have been described what are at present considered to be certain embodiments of the invention, it will be understood that various modifications may be made thereto, and it is intended that the appended claim cover all such modifications as fall within the true spirit and scope of the invention.

What is claimed is:

1. A method of manufacturing an organic electroluminescent display device, comprising the steps of:

forming a first insulating layer on a substrate having a rectangular display area and a frame area which surrounds an outer periphery of the display area;

forming a first patterning layer on the first insulating layer;

forming a second patterning layer on the first patterning layer;

removing apart of the second patterning layer and the first patterning layer in the frame area to form a trench portion; and

forming an electrode layer on the second patterning layer and in the trench portion, wherein

in the step of forming the trench portion, an end of the first patterning layer exposed within the trench portion is etched to an outside more than an end of the second patterning layer exposed within the trench portion in a plan view, and

in the step of forming the electrode layer, the electrode layer formed within the trench portion which is located on a lower side of the end of the first patterning layer is isolated from the electrode layer formed outside of the trench portion, which is located on an upper side of the end of the first patterning layer.

2. The method of manufacturing an organic electroluminescent display device according to claim 1, wherein

a plurality of the display areas is arrayed in a matrix on the substrate,

the trench portion is formed along an outer periphery of the display area in the plan view, and

the frame area is cut along the trench portion after the electrode layer is formed to divide the substrate into a plurality of pieces.

3. The method of manufacturing an organic electroluminescent display device according to claim 1, further comprising the step of:

forming a ground in the frame area of the substrate before the step of forming the first insulating layer, wherein

in the step of forming the trench portion, the ground is exposed within the trench portion, and

in the step of forming the electrode layer, the electrode layer is connected to the ground exposed within the trench portion.

4. The method of manufacturing an organic electroluminescent display device according to claim 1, wherein

at least a part of a plurality of the trench portions are aligned at intervals from each other, and

in the step of forming the electrode layer, the electrode layer formed in the part of trench portion is isolated from the electrode layer formed between the part of trench portions to form the terminal having the electrode layer within the part of trench portion.

5. The method of manufacturing an organic electroluminescent display device according to claim 1,

wherein the second patterning layer is a pixel electrode layer, and the electrode layer is a counter electrode layer facing the pixel electrode layer.

6. The method of manufacturing an organic electroluminescent display device according to claim 1,

wherein in the step of forming electrode layer, a material of the electrode layer is deposited on the second patterning layer with the use of a mask having a shielding portion extending in only one direction in correspondence with a part of the frame area to form an area in which the electrode layer is not formed in a part of the frame area.

7. An organic electroluminescent display device comprising:

a substrate having a rectangular display area and a frame area which surrounds an outer periphery of the display area;

a first insulating layer that is formed on the substrate;

a first patterning layer that is formed on the first insulating layer;

a second patterning layer that is formed on the first patterning layer;

a trench portion that is formed in the frame area, and from which a part of the second patterning layer and the first patterning layer are removed; and

an electrode layer that is formed on the second patterning layer and within the trench portion, wherein

an end of the first patterning layer exposed within the trench portion is located outside of an end of the second patterning layer exposed within the trench portion in a plan view, and

the electrode layer that is formed within the trench portion which is located on a lower side of the end of the first patterning layer is isolated from the electrode layer that is formed in a periphery of the trench portion which is located on an upper side of the end of the first patterning layer.

* * * * *

专利名称(译)	有机电致发光显示装置和制造有机电致发光显示装置的方法		
公开(公告)号	US20150076476A1	公开(公告)日	2015-03-19
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申请(专利权)人(译)	日本展示INC.		
当前申请(专利权)人(译)	JAPAN DISPLAY INC		
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摘要(译)

一种制造有机电致发光显示装置的方法，包括步骤：在基板上形成第一绝缘层；形成第一图案层；形成第二图案层；形成沟槽部分；在所述第二图案化层和所述沟槽部分中形成电极层，其中在形成所述沟槽部分的步骤中，在所述沟槽部分内暴露的所述第一图案化层的一端被蚀刻到比所述第二图案化层的末端更多的一端。在平面图中暴露在沟槽部分内的图案化层，并且在形成电极层的步骤中，形成在沟槽部分内的电极层与形成在沟槽部分外部的电极层隔离。

A method of manufacturing an organic electroluminescent display device includes the steps of: forming a first insulating layer on a substrate; forming a first patterning layer; forming a second patterning layer; forming a trench portion; and forming an electrode layer on the second patterning layer and in the trench portion, wherein in the step of forming the trench portion, an end of the first patterning layer exposed within the trench portion is etched to an outside more than an end of the second patterning layer exposed within the trench portion in a plan view, and in the step of forming the electrode layer, the electrode layer formed within the trench portion is isolated from the electrode layer formed outside of the trench portion.